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IN THE CLAIMS:

Please amend the claims as shown in the following listing of claims. This listing of claims will replace all prior versions, and listings, of claims in the application:

(Currently Amended) A method of manufacturing a thermoset including the steps
of:

providing a base thermoset component;

adding expandable hollow microspheres to at least one of the base thermoset component[[s]] in the liquid phase; and

applying heat treatment to a thermoset mixture comprising the base thermoset component and the expandable hollow microspheres the partially or fully oured thermoset, wherein eausing the expandable hollow microspheres [[to]] expand during, or after, a partial or full curing of the thermoset mixture such that a permanent deformation occurs around the microspheres and compressive residual stress is created in the thermoset mixture.

- (Currently Amended) A method as claimed in claim 1 wherein the thermoset
 mixture comprises an epoxy resin and the expandable hollow microspheres are added
 to the epoxy resin component.
- 3. (Currently Amended) A method as claimed in claim 2 <u>further including the step of adding a curing agent to the thermoset mixture</u>. wherein the mixture of epoxy component and microspheres are heated for easy mixing before adding a curing agent.

- 4. (Currently Amended) A method as claimed in claim 3 wherein the <u>curing agent is</u>

 added after said applying heat treatment, mixture is allowed to cool before adding the ouring agent.
- 5. (Original) A method as claimed in claim 3 wherein the mixture is stirred after adding the curing agent, and poured into a mould for curing.
- 6. (Currently Amended) A method as claimed in claim 1 wherein the expandable hollow microspheres comprise consist of a co-polymer shell and gas.
- 7. (Currently Amended) A method as claimed in claim 3 [[4]] wherein the curing agent is added before said applying heat treatment. eurod epoxy system is heated to create compressive residual stress around the expandable hollow microspheres.